

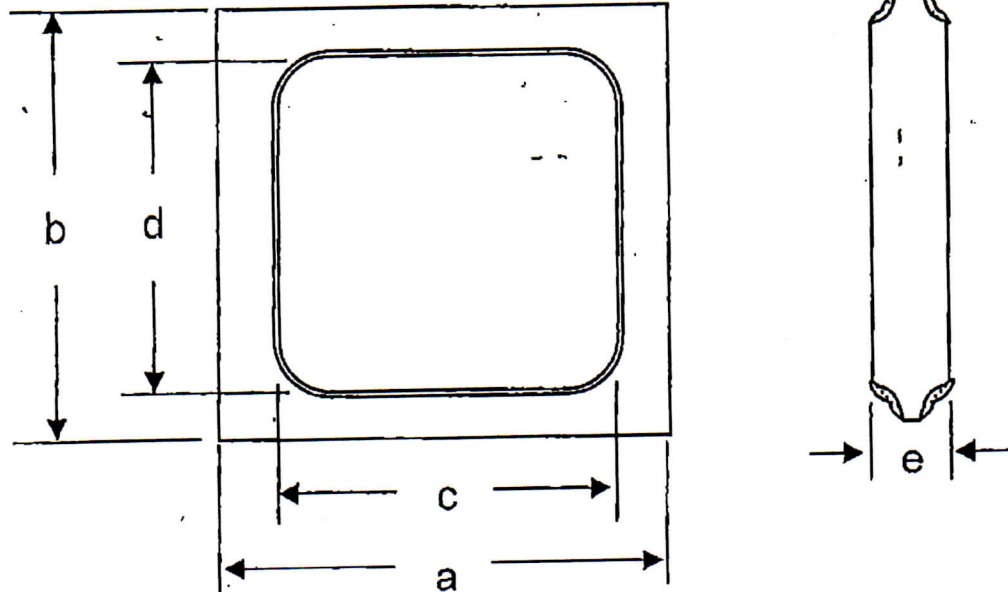


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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



TGxxxCxxxSDA : Bi-direction, Vwm 5.0V~188V

Unit: Inch (mm)	a, b	c, d	e	Available Voltage
TG060CxxxSDA	$\frac{0.060 (1.52)}{0.058 (1.47)}$	$\frac{0.042 (1.07)}{0.040 (1.02)}$	$\frac{0.0155 (0.39)}{0.0125 (0.32)}$	5.0V ~ 188V

Top Material: Au
 Backside Material: Au
 Bond Pad Size: .042" Squ.
 Backside Potential: Bi Directional
 Mask Ref:

APPROVED BY: DK

DIE SIZE .060" Square

DATE: 8/24/12

MFG: DALE

THICKNESS .015" Max.

P/N: TG060C090S4PC